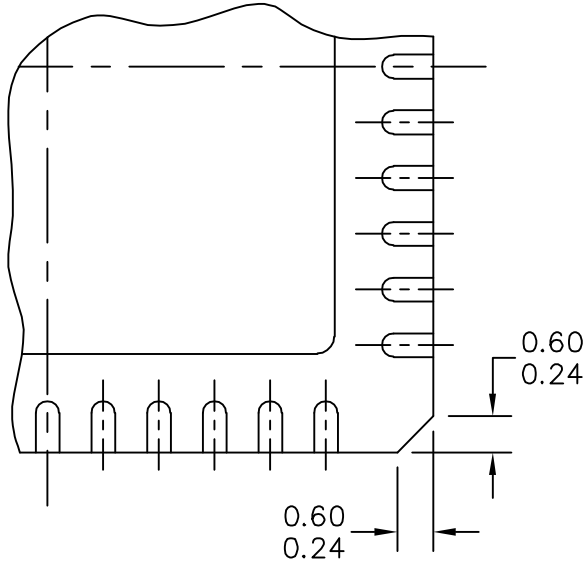
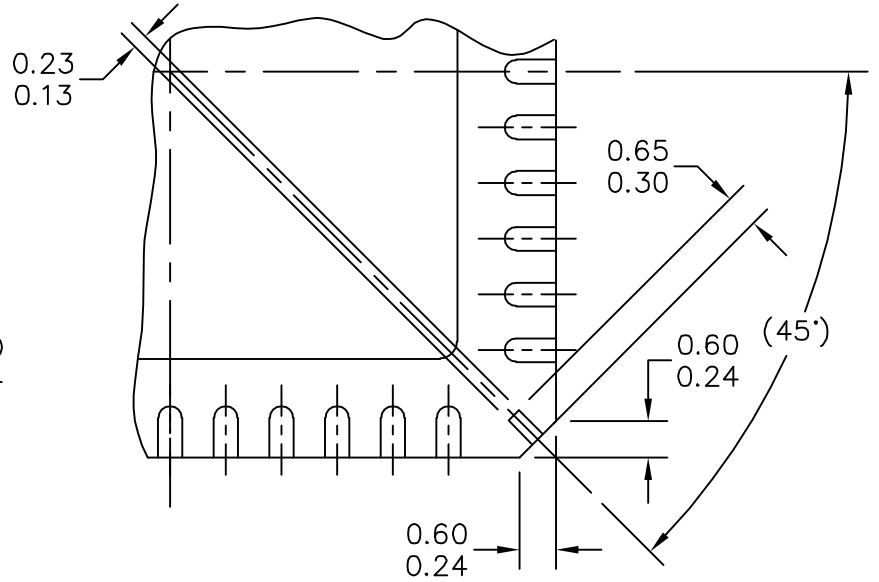


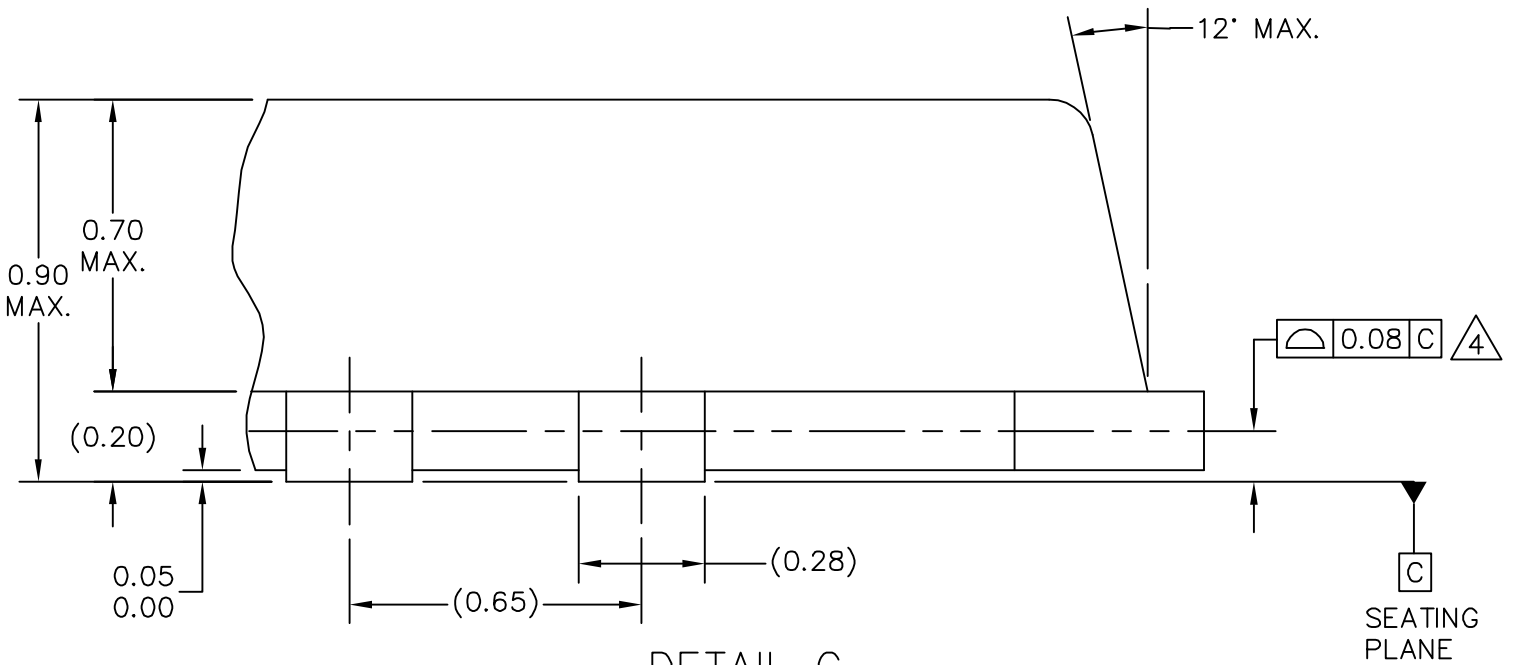
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TITLE: THERMALLY ENHANCED QUAD FLAT NON-LEADED PACKAGE (QFN) 44 TERMINAL, 0.65 PITCH (9 X 9 X 1)	DOCUMENT NO: 98ARH99034A	REV: G
	STANDARD: FREESCALE STD	
	SOT1113-2	05 FEB 2016



DETAIL N
PREFERRED CORNER CONFIGURATION

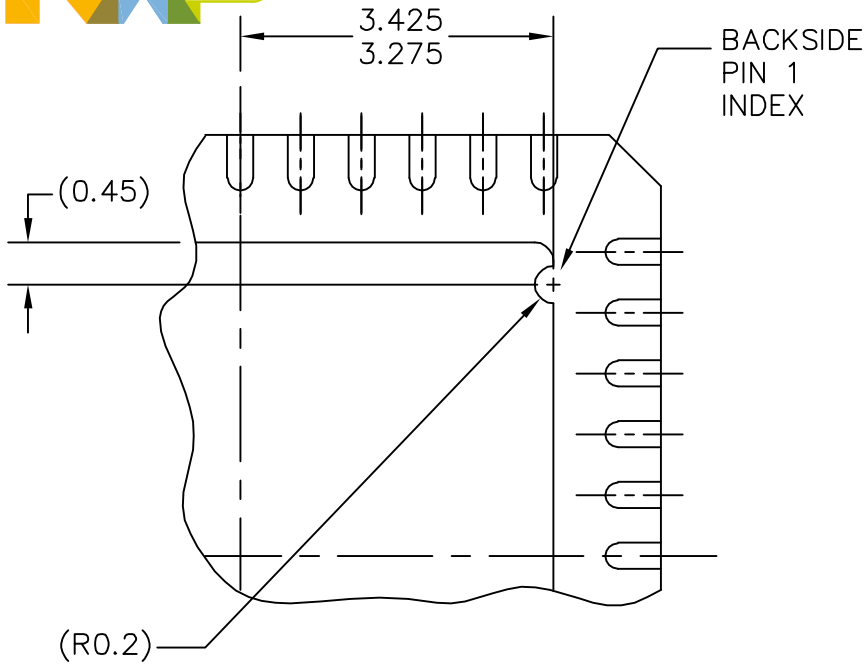


DETAIL N
CORNER CONFIGURATION OPTION

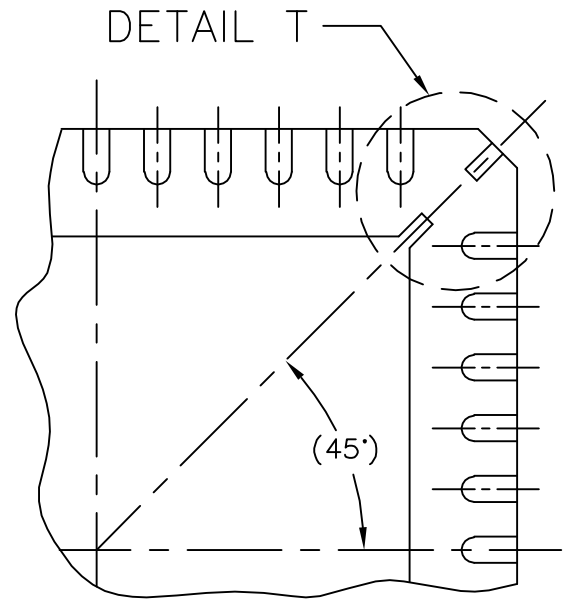


DETAIL G
VIEW ROTATED 90° CW

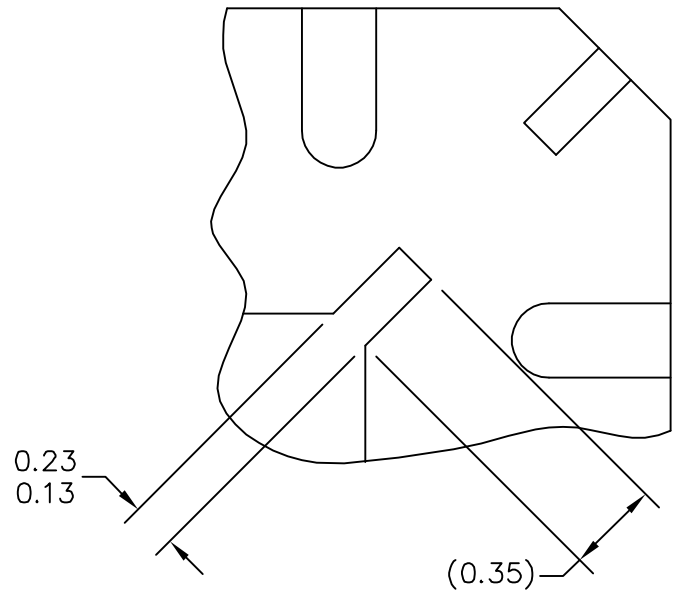
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TITLE: THERMALLY ENHANCED QUAD FLAT NON-LEADED PACKAGE (QFN) 44 TERMINAL, 0.65 PITCH (9 X 9 X 1)	DOCUMENT NO: 98ARH99034A	REV: G
	STANDARD: FREESCALE STD	
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DETAIL M
PREFERRED BACKSIDE PIN 1 INDEX



DETAIL M
BACKSIDE PIN 1 INDEX OPTION




DETAIL T
BACKSIDE PIN 1 INDEX OPTION

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	STANDARD: FREESCALE STD	
	SOT1113-2	05 FEB 2016



NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. THE COMPLETE JEDEC DESIGNATOR FOR THIS PACKAGE IS: HF-PQFN.
4.  COPLANARITY APPLIES TO LEADS, CORNER LEADS AND DIE ATTACH PAD.
5. FOR ANVIL SINGULATED QFN PACKAGES, MAXIMUM DRAFT ANGLE IS 12°.
6. MIN METAL GAP SHOULD BE 0.25MM.

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		STANDARD: FREESCALE STD	
		SOT1113-2	05 FEB 2016